# TPS731 Capacitor-Free, NMOS, 150mA, Low-Dropout Regulator With Reverse Current Protection

## 1 Features

- Stable with or without capacitors of all types
- Input voltage range of 1.7V to 5.5V
- Ultra-low dropout voltage: 30mV typical (150mA load)
- Excellent load transient response—with or without optional output capacitor
- New NMOS topology provides low reverse leakage current
- Low noise: 30μ$V_{RMS}$ typical (10kHz to 100kHz)
- 0.5% initial accuracy
- 1% overall accuracy over line, load, and temperature
- Less than 1μA maximum $I_Q$ in shutdown mode
- Thermal shutdown and specified minimum and maximum current-limit protection
- Available in multiple output voltage versions:
  - Fixed outputs: 1.20V to 5V
  - Adjustable outputs: 1.2V to 5.5V
  - Custom outputs available

## 2 Applications

- Smart grid and energy
- Building automation
- Set-top boxes
- Medical equipment
- Test and measurement
- Point-of-sale terminals
- Wireless infrastructure

## 3 Description

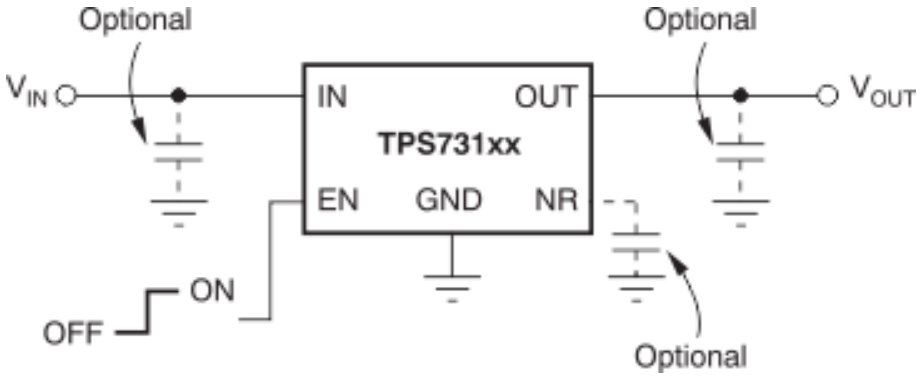
The TPS731 low-dropout (LDO) linear voltage regulator uses an NMOS pass transient in a voltage-follower configuration. This topology is stable using output capacitors with low equivalent series resistance (ESR), and even allows operation without a capacitor. The device also provides high reverse blockage (low reverse current) and ground pin current that is nearly constant over all values of output current.

The TPS731 uses an advanced BiCMOS process to yield high precision while delivering very low dropout voltages and low ground pin current. Current consumption, when not enabled, is less than 1μA and is designed for portable applications. The extremely low output noise (30μ$V_{RMS}$ with 0.1μF $C_{NR}$) is designed for powering VCOs. This device is protected by thermal shutdown and foldback current limit.

**Package Information**

| PART NUMBER | PACKAGE(1) | PACKAGE SIZE(2) |
|---|---|---|
| TPS731 | DBV (SOT-23, 5) | 2.9mm × 2.8mm |

(1) For more information, see Mechanical, Packaging, and Orderable Information.
(2) The package size (length × width) is a nominal value and includes pins, where applicable.




**Typical Application Circuit for Fixed-Voltage Versions**

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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# 4 Pin Configuration and Functions

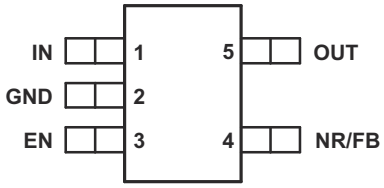


**Figure 4-1. DBV Package, 5-Pin SOT-23, Top View**

**Table 4-1. Pin Functions**

| PIN | | TYPE[1] | DESCRIPTION |
|---|---|---|---|
| NAME | NO. | | |
| EN | 3 | I | Driving the enable pin (EN) high turns on the regulator. Driving this pin low puts the regulator into shutdown mode. See the *Enable Pin and Shutdown* section for more details. EN can be connected to IN if not used. |
| FB | 4 | I | Adjustable-voltage version only—this is the input to the control loop error amplifier, and is used to set the output voltage of the device. |
| GND | 2 | — | Ground. |
| IN | 1 | I | Input supply. |
| NR | 4 | — | Fixed-voltage versions only—connecting an external capacitor to this pin bypasses noise generated by the internal bandgap, reducing output noise to very low levels. |
| OUT | 5 | O | Output of the regulator. There are no output capacitor requirements for stability. |

(1) I = input, O = output

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# 5 Specifications

## 5.1 Absolute Maximum Ratings

over operating junction temperature range (unless otherwise noted)[1]

| | | MIN | MAX | UNIT |
|---|---|---|---|---|
| Voltage | Input, $V_{IN}$ | –0.3 | 6 | V |
| | Enable, $V_{EN}$ | –0.3 | 6 | |
| | Output, $V_{OUT}$ | –0.3 | 5.5 | |
| | $V_{NR}$, $V_{FB}$ | –0.3 | 6 | |
| Current | Maximum output, $I_{OUT}$ | Internally limited | | |
| Output short-circuit duration | | Indefinite | | |
| Continuous total power dissipation | $P_{DISS}$ | See *Thermal Information* | | |
| Temperature | Operating junction, $T_J$ | –55 | 150 | °C |
| | Storage, $T_{stg}$ | –65 | 150 | |

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.

## 5.2 ESD Ratings

| | | | VALUE | UNIT |
|---|---|---|---|---|
| $V_{(ESD)}$ | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins[1] | ±2000 | V |
| | | Charged-device model (CDM), per JEDEC specification JESD22-C101, all pins[2] | ±500 | |

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

## 5.3 Recommended Operating Conditions

over operating junction temperature range (unless otherwise noted)

| | | MIN | NOM | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{IN}$ | Input supply voltage | 1.7 | | 5.5 | V |
| $I_{OUT}$ | Output current | 0 | | 150 | mA |
| $T_J$ | Operating junction temperature | –40 | | 125 | °C |

## 5.4 Thermal Information

| THERMAL METRIC[1] | | TPS731 New silicon DBV (SOT-23) 5 PINS | TPS731 Legacy silicon DBV (SOT-23) 5 PINS | UNIT |
|---|---|---|---|---|
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 185.2 | 207.2 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 82.9 | 124.2 | °C/W |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 53.1 | 35 | °C/W |
| $\psi_{JT}$ | Junction-to-top characterization parameter | 21.1 | 13.5 | °C/W |
| $\psi_{JB}$ | Junction-to-board characterization parameter | 52.7 | 34.1 | °C/W |

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application note.


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## 5.5 Electrical Characteristics

Over operating temperature range ($T_J$ = –40°C to 125°C), $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V[1] , $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted). Typical values are at $T_J$ = 25°C

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|---|---|---|---|---|---|---|---|
| $V_{IN}$ | Input voltage range[1] | | | 1.7 | | 5.5 | V |
| $V_{FB}$ | Internal reference (TPS73101) | $T_J$ = 25°C | | 1.198 | 1.204 | 1.210 | V |
| $V_{OUT}$ | Output voltage range (TPS73101)[2] | | | $V_{FB}$ | | 5.5 - $V_{DO}$ | V |
| | Accuracy[1] [3] | Nominal | $T_J$ = 25°C | –0.5 | | 0.5 | % |
| | | $V_{IN}$, $I_{OUT}$, and T | $V_{OUT}$ + 0.5V ≤ $V_{IN}$ ≤ 5.5V; 10mA ≤ $I_{OUT}$ ≤ 150mA | –1 | ±0.5 | 1 | |
| $\Delta V_{OUT(\Delta VIN)}$ | Line regulation [1] | $V_{OUT(nom)}$ + 0.5V ≤ $V_{IN}$ ≤ 5.5V | | | 0.01 | | %/V |
| $\Delta V_{OUT(\Delta IOUT)}$ | Load regulation | 1mA ≤ $I_{OUT}$ ≤ 150mA | | | 0.002 | | %/mA |
| $\Delta V_{OUT(\Delta IOUT)}$ | Load regulation | 10mA ≤ $I_{OUT}$ ≤ 150mA | | | 0.0005 | | %/mA |
| $V_{DO}$ | Dropout voltage[4] ($V_{IN}$ = $V_{OUT(NOM)}$ - 0.1V) | $I_{OUT}$ = 150mA | | | 30 | 100 | mV |
| $Z_{O(DO)}$ | Output impedance in dropout | 1.7V ≤ $V_{IN}$ ≤ $V_{OUT}$ + $V_{DO}$ | | | 0.25 | | Ω |
| $I_{CL}$ | Output current limit | $V_{OUT}$ = 0.9 × $V_{OUT(nom)}$ | | 150 | 360 | 500 | mA |
| $I_{SC}$ | Short-circuit current | $V_{OUT}$ = 0V | | | 200 | | mA |
| $I_{REV}$ | Reverse leakage current[5] (-$I_{IN}$) | $V_{EN}$ ≤ 0.5V, 0V ≤ $V_{IN}$ ≤ $V_{OUT}$ | | | 0.1 | 10 | µA |
| $I_{GND}$ | Ground pin current | $I_{OUT}$ = 10mA ($I_Q$), legacy silicon | | | 400 | 550 | µA |
| | | $I_{OUT}$ = 10mA ($I_Q$), new silicon | | | 400 | 630 | |
| $I_{GND}$ | Ground pin current | $I_{OUT}$ = 10mA ($I_Q$), $V_{OUT}$ = 5V only, new silicon | | | 580 | 700 | µA |
| $I_{GND}$ | Ground pin current | $I_{OUT}$ = 150mA | | | 550 | 750 | µA |
| $I_{GND}$ | Ground pin current | $I_{OUT}$ = 150mA, $V_{OUT}$ = 5V only, new silicon | | | 700 | 850 | µA |
| $I_{SHDN}$ | Shutdown current ($I_{GND}$) | $V_{EN}$ ≤ 0.5V, $V_{OUT}$ ≤ $V_{IN}$ ≤ 5.5V, –40°C ≤ $T_J$ ≤ 100°C, legacy silicon | | | 0.02 | 1 | µA |
| | | $V_{EN}$ ≤ 0.5V, $V_{OUT}$ ≤ $V_{IN}$ ≤ 5.5V, new silicon | | | 0.02 | 1 | |
| $I_{FB}$ | Feedback pin current (TPS73101) | | | | 0.1 | 0.3 | µA |
| PSRR | Power-supply rejection ratio (ripple rejection) | f = 100Hz, $I_{OUT}$ = 150mA | | | 58 | | dB |
| | | f = 10kHz, $I_{OUT}$ = 150mA | | | 37 | | |
| $V_N$ | Output noise voltage, BW = 10Hz to 100kHz | $C_{OUT}$ = 10µF, no $C_{NR}$ | | | 27 × $V_{OUT}$ | | $\mu V_{RMS}$ |
| | | $C_{OUT}$ = 10µF, $C_{NR}$ =0.01µF | | | 8.5 × $V_{OUT}$ | | |
| $t_{STR}$ | Startup time | $V_{OUT}$ = 3V, $R_L$ = 30Ω, $C_{OUT}$ = 1µF, $C_{NR}$ = 0.01µF | | | 600 | | µs |
| $V_{EN(high)}$ | EN pin high (enabled) | | | 1.7 | | $V_{IN}$ | V |
| $V_{EN(low)}$ | EN pin low (shutdown) | | | 0 | | 0.5 | V |
| $I_{EN(high)}$ | Enable pin current (enabled) | $V_{EN}$ = 5.5V | | | 0.02 | 0.1 | µA |
| $T_{SD}$ | Thermal shutdown temperature | Shutdown, temperature increasing | | | 160 | | °C |
| | | Reset, temperature decreasing | | | 140 | | |
| $T_J$ | Operating junction temperature | | | –40 | | 125 | °C |

(1) Minimum $V_{IN}$ = $V_{OUT}$ + $V_{DO}$ or 1.7V, whichever is greater.
(2) TPS73101 is tested at $V_{OUT}$ = 2.5V.
(3) Tolerance of external resistors not included in this specification.
(4) $V_{DO}$ is not measured for output versions with $V_{OUT(nom)}$ < 1.8V, because minimum $V_{IN}$ = 1.7V.
(5) Fixed-voltage versions only; refer to *Application Information* section for more information.

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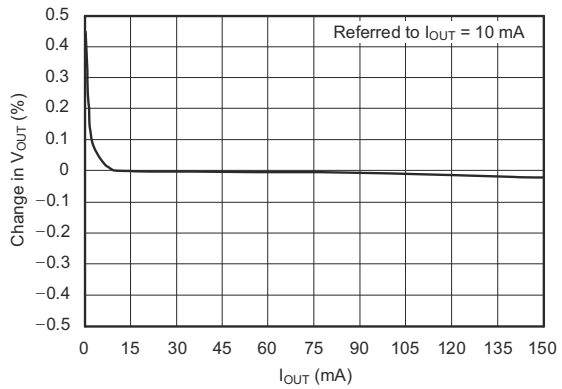
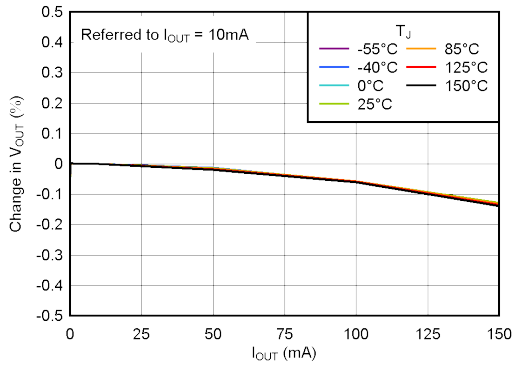
## 5.6 Typical Characteristics

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



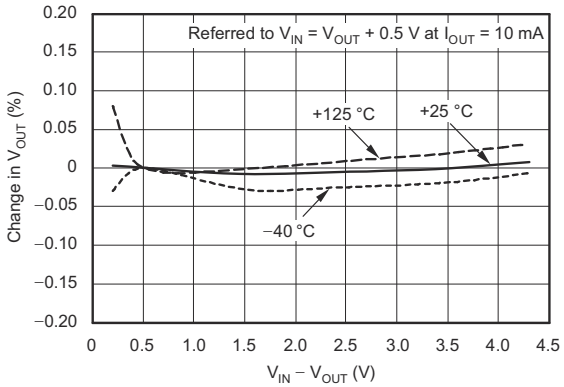

Legacy silicon

**Figure 5-1. Load Regulation**



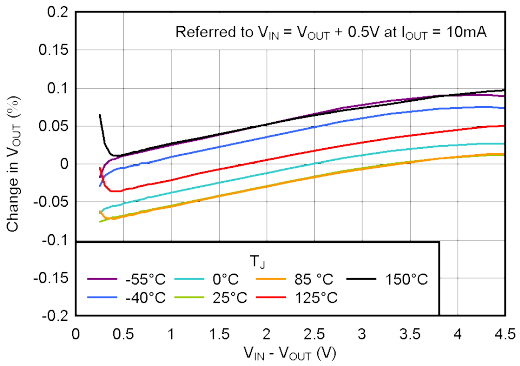

New silicon

**Figure 5-2. Load Regulation**



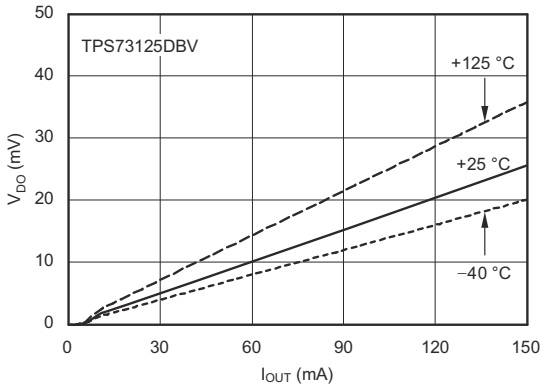

Legacy silicon

**Figure 5-3. Line Regulation**



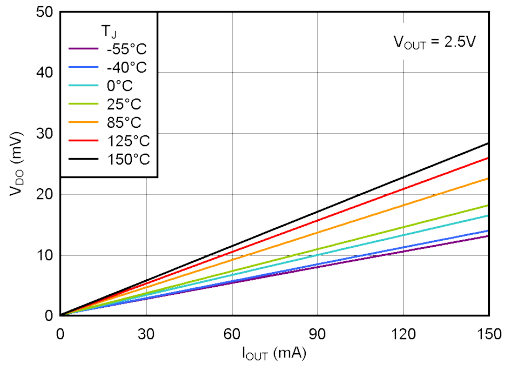

New silicon

**Figure 5-4. Line Regulation**




Legacy silicon

**Figure 5-5. Dropout Voltage vs Output Current**




New silicon

**Figure 5-6. Dropout Voltage vs Output Current**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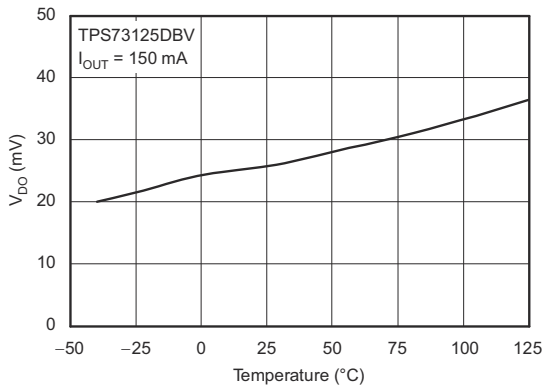
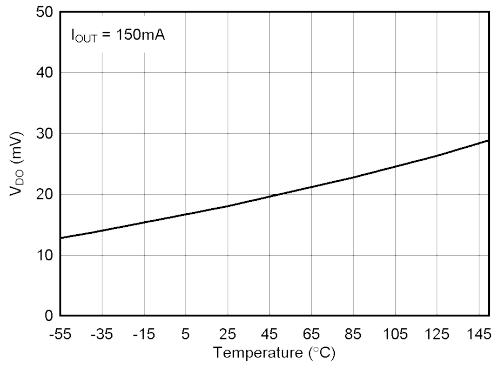
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



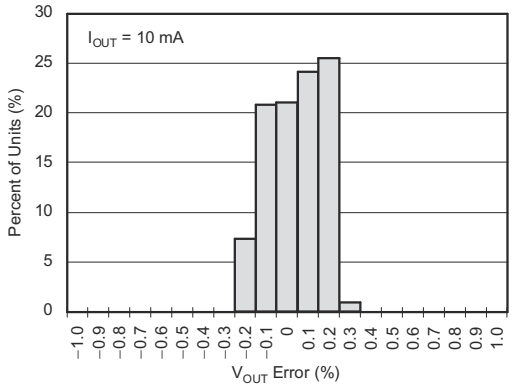

Legacy silicon

**Figure 5-7. Dropout Voltage vs Temperature**



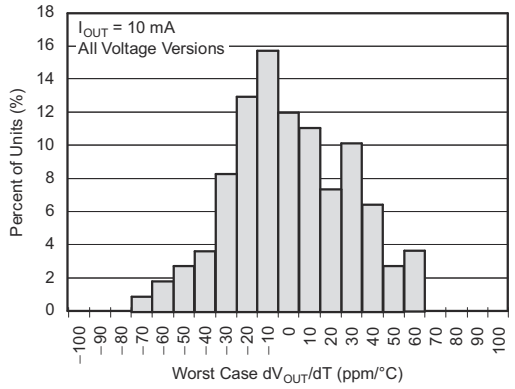

New silicon

**Figure 5-8. Dropout Voltage vs Temperature**



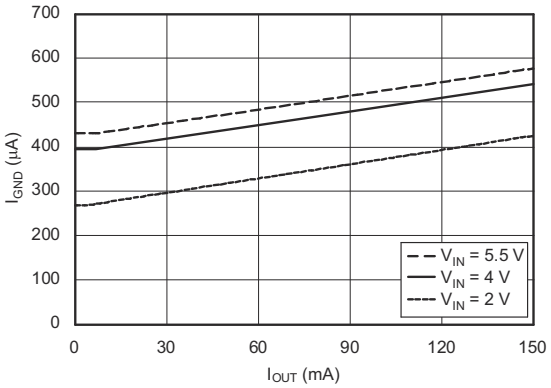

Legacy silicon

**Figure 5-9. Output Voltage Accuracy Histogram**



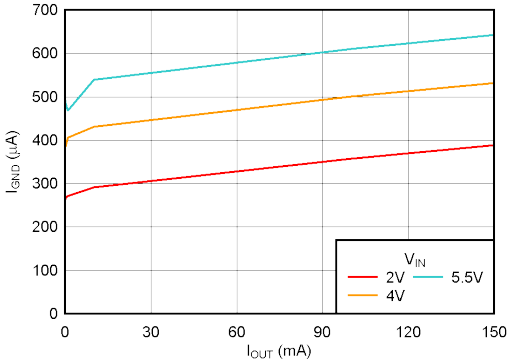

Legacy silicon

**Figure 5-10. Output Voltage Drift Histogram**




Legacy silicon

**Figure 5-11. Ground Pin Current vs Output Current**

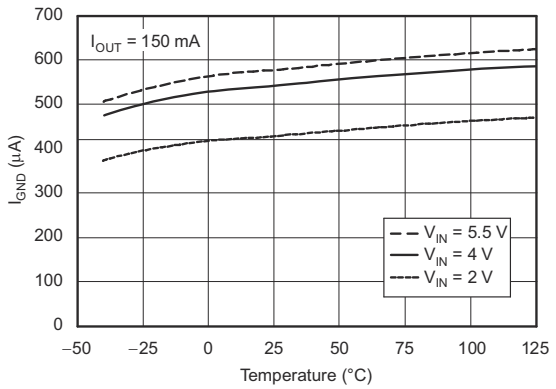



New silicon

**Figure 5-12. Ground Pin Current vs Output Current**

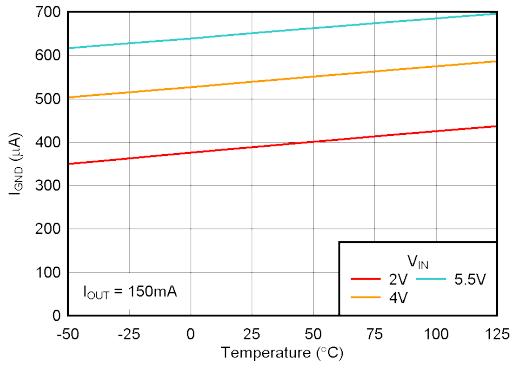
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



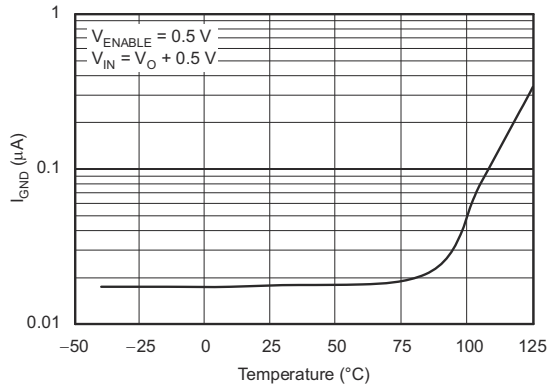

Legacy silicon

**Figure 5-13. Ground Pin Current vs Temperature**



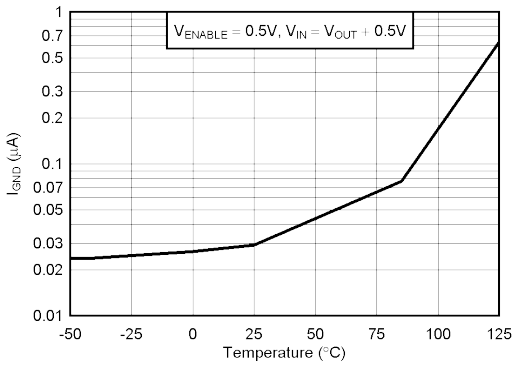

New silicon

**Figure 5-14. Ground Pin Current vs Temperature**



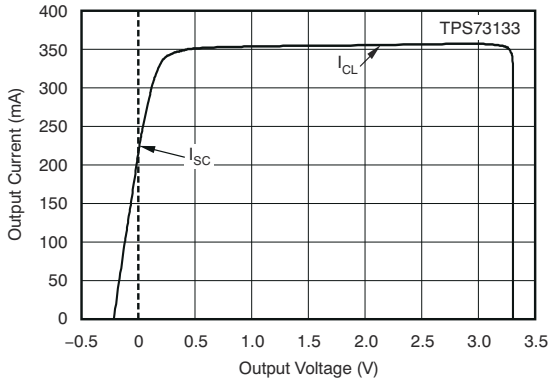

Legacy silicon

**Figure 5-15. Ground Pin Current in Shutdown vs Temperature**




New silicon

**Figure 5-16. Ground Pin Current in Shutdown vs Temperature**




Legacy silicon

**Figure 5-17. Current Limit vs $V_{OUT}$ (Foldback)**

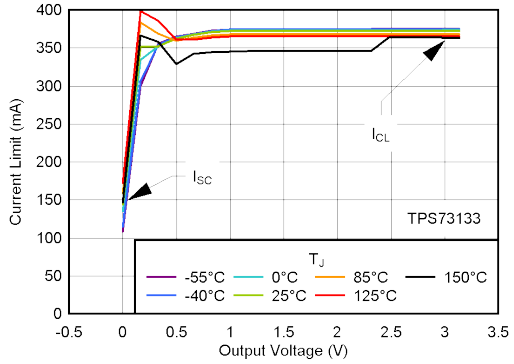



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**Figure 5-18. Current Limit vs $V_{OUT}$ (Foldback)**


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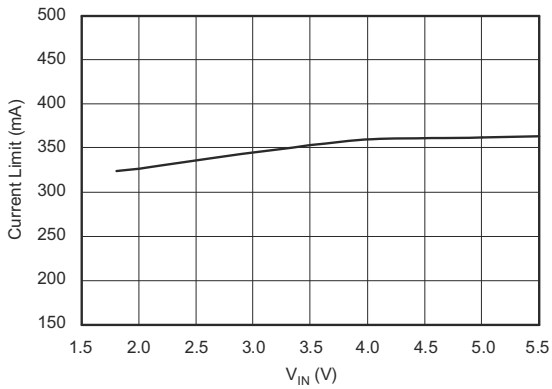
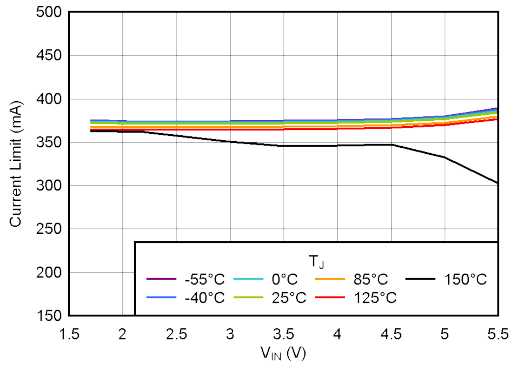
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



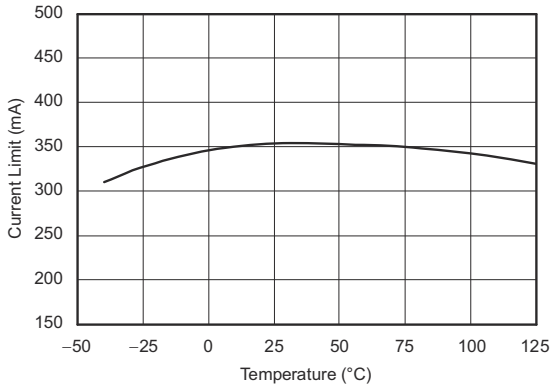

Legacy silicon

**Figure 5-19. Current Limit vs $V_{IN}$**



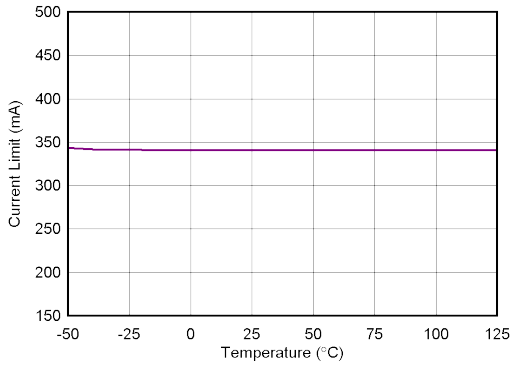

New silicon

**Figure 5-20. Current Limit vs $V_{IN}$**



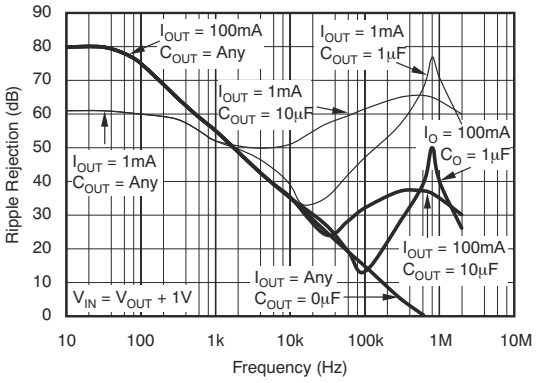

Legacy silicon

**Figure 5-21. Current Limit vs Temperature**



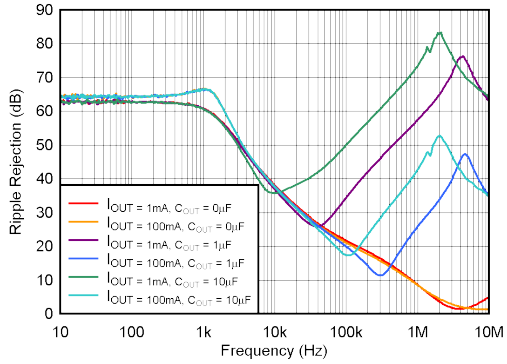

New silicon

**Figure 5-22. Current Limit vs Temperature**




Legacy silicon

**Figure 5-23. PSRR (Ripple Rejection) vs Frequency**

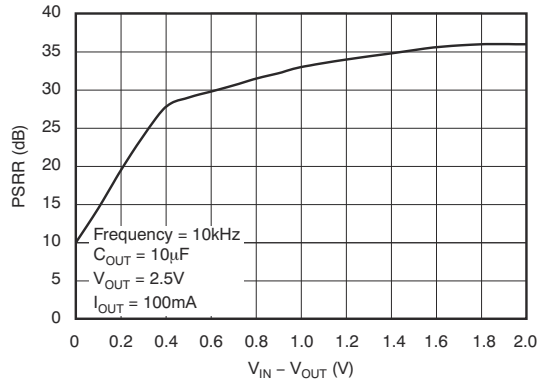



New silicon

**Figure 5-24. PSRR (Ripple Rejection) vs Frequency**

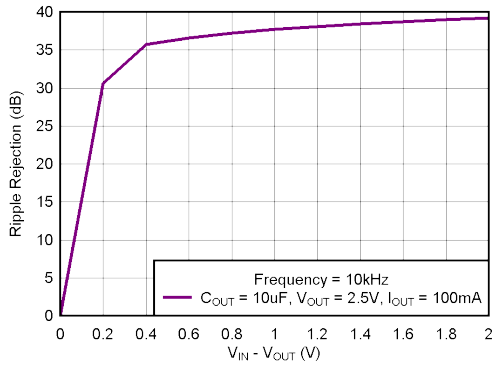
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



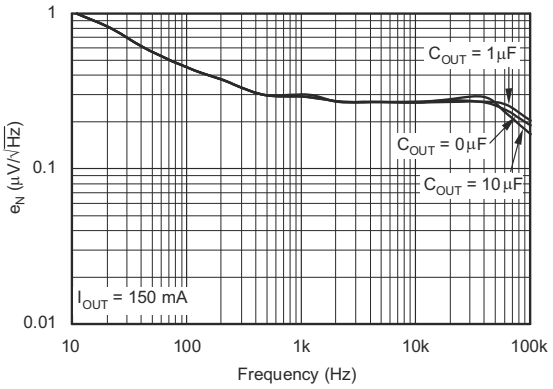

Legacy silicon

**Figure 5-25. PSRR (Ripple Rejection) vs $V_{IN}$ – $V_{OUT}$**



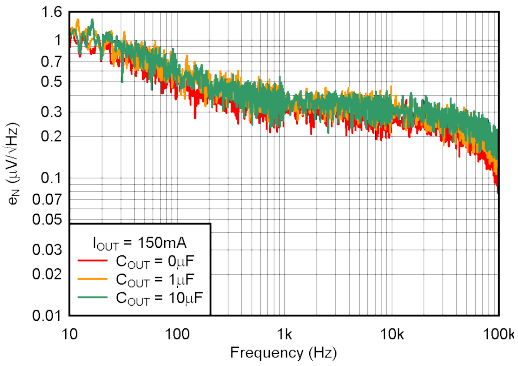

New silicon

**Figure 5-26. PSRR (Ripple Rejection) vs ($V_{IN}$ – $V_{OUT}$)**



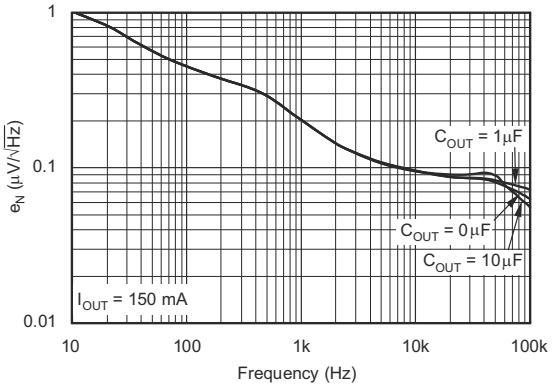

Legacy silicon

**Figure 5-27. Noise Spectral Density $C_{NR}$ = 0µF**



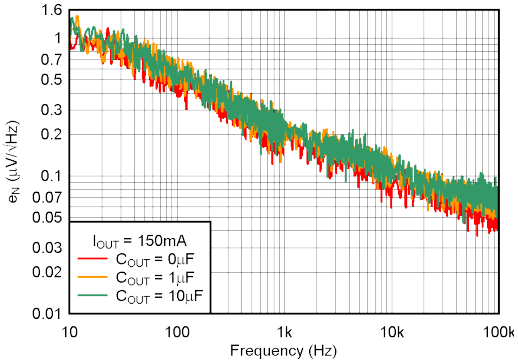

New silicon

**Figure 5-28. Noise Spectral Density $C_{NR}$ = 0µF**




Legacy silicon

**Figure 5-29. Noise Spectral Density $C_{NR}$ = 0.01µF**




New silicon

**Figure 5-30. Noise Spectral Density $C_{NR}$ = 0.01µF**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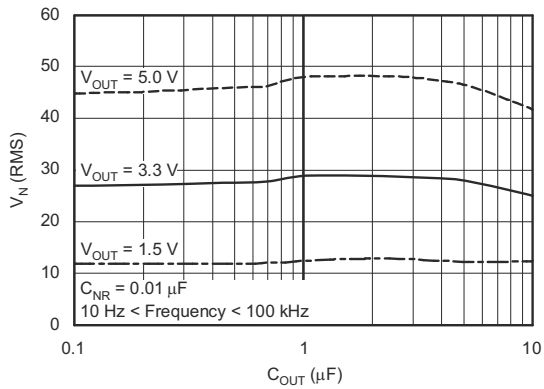
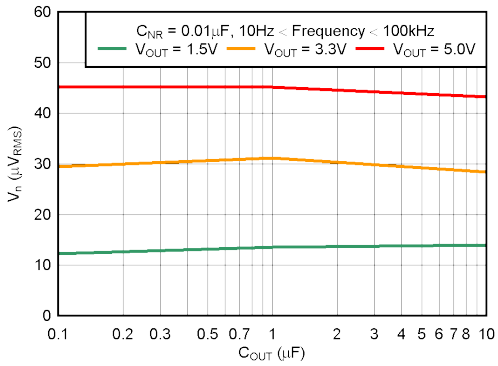
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



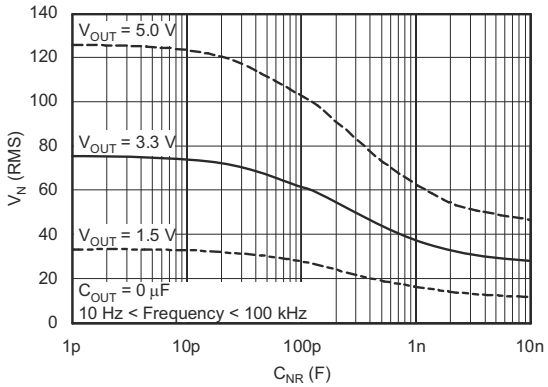

Legacy silicon

**Figure 5-31. RMS Noise Voltage vs $C_{OUT}$**



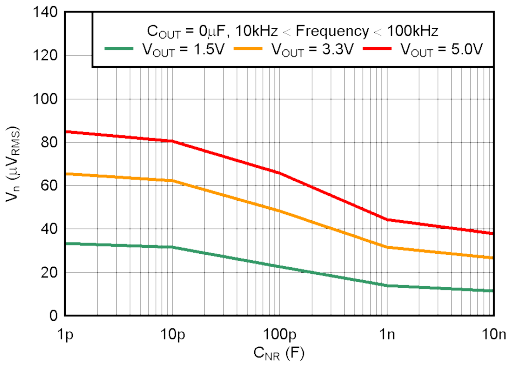

New silicon

**Figure 5-32. RMS Noise Voltage vs $C_{OUT}$**



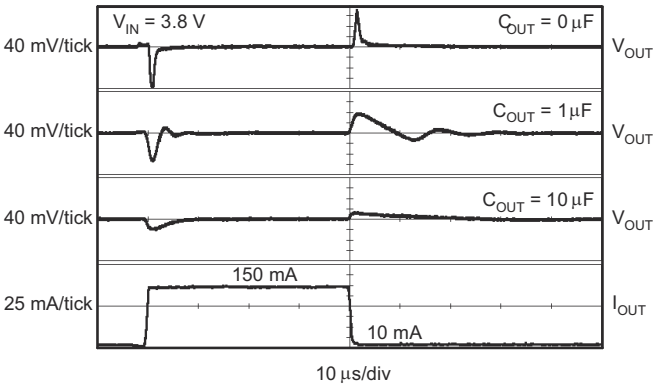

Legacy silicon

**Figure 5-33. RMS Noise Voltage vs $C_{NR}$**



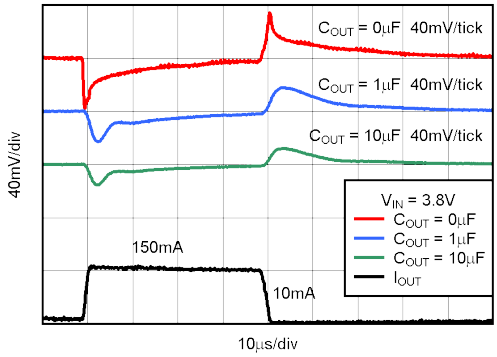

New silicon

**Figure 5-34. RMS Noise Voltage vs $C_{NR}$**




Legacy silicon

**Figure 5-35. TPS73133 Load Transient Response**

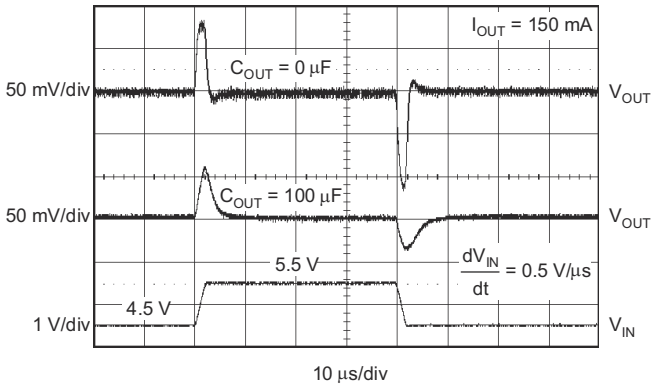



New silicon

**Figure 5-36. TPS73133 Load Transient Response**

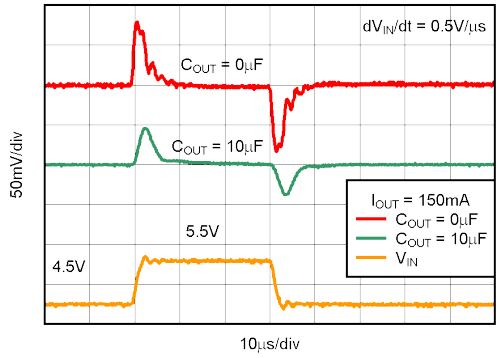
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



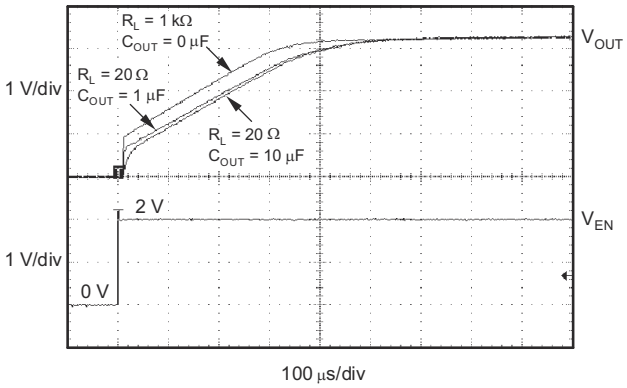

Legacy silicon

**Figure 5-37. TPS73133 Line Transient Response**



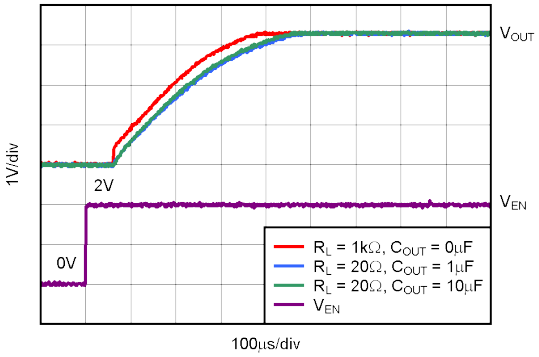

New silicon

**Figure 5-38. TPS73133 Line Transient Response**



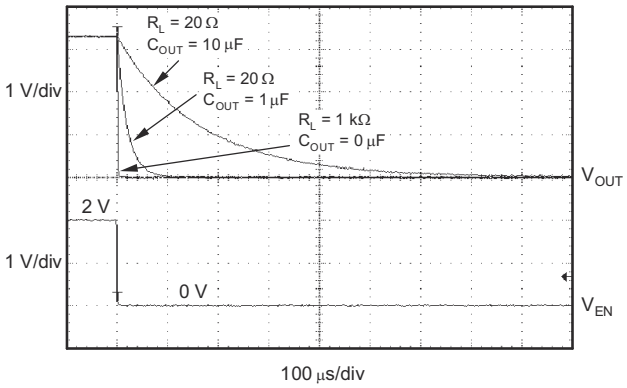

Legacy silicon

**Figure 5-39. TPS73133 Turn-On Response**



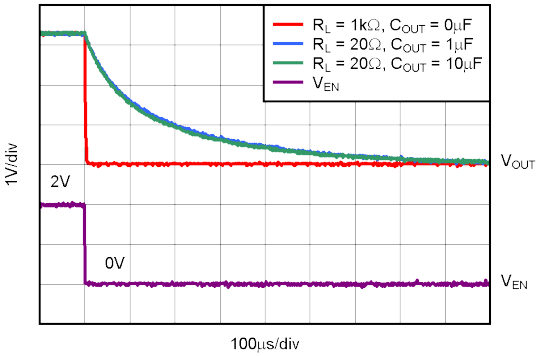

New silicon

**Figure 5-40. TPS73133 Turn-On Response**




Legacy silicon

**Figure 5-41. TPS73133 Turn-Off Response**




New silicon

**Figure 5-42. TPS73133 Turn-Off Response**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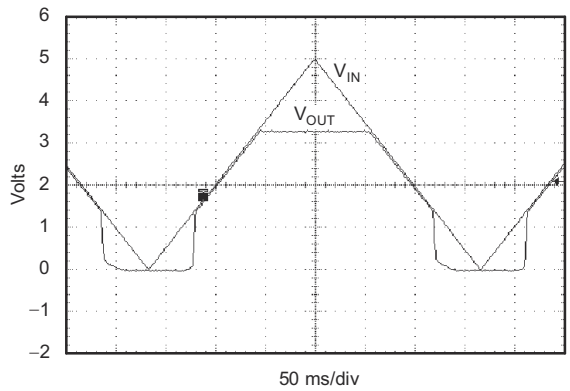
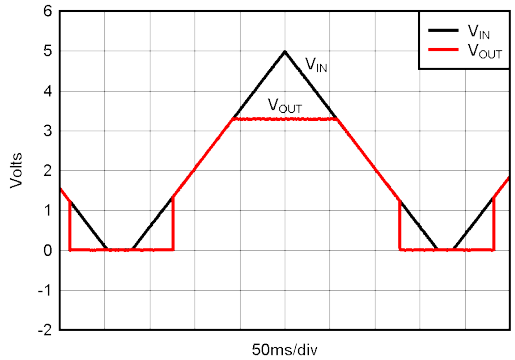
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



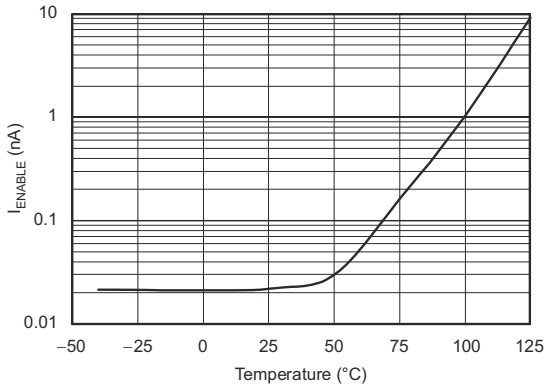

Legacy silicon

**Figure 5-43. TPS73133 Power-Up and Power-Down**



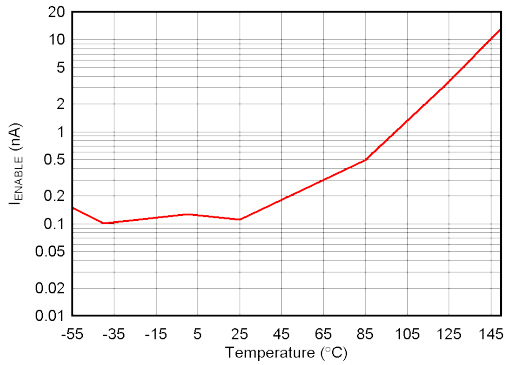

New silicon

**Figure 5-44. TPS73133 Power-Up and Power-Down**



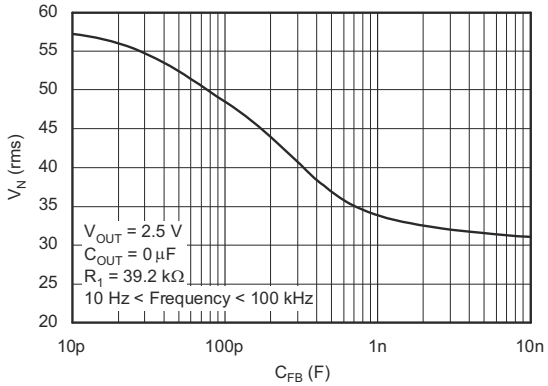

Legacy silicon

**Figure 5-45. $I_{ENABLE}$ vs Temperature**



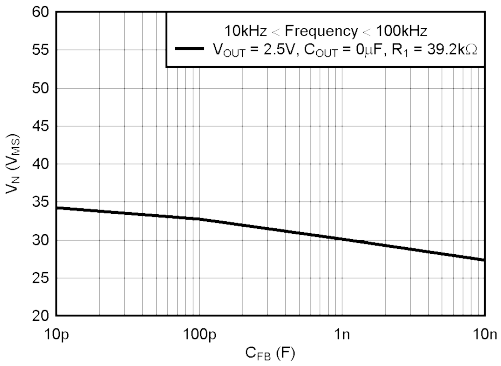

New silicon

**Figure 5-46. $I_{ENABLE}$ vs Temperature**




Legacy silicon

**Figure 5-47. TPS73101 RMS Noise Voltage vs $C_{FB}$**

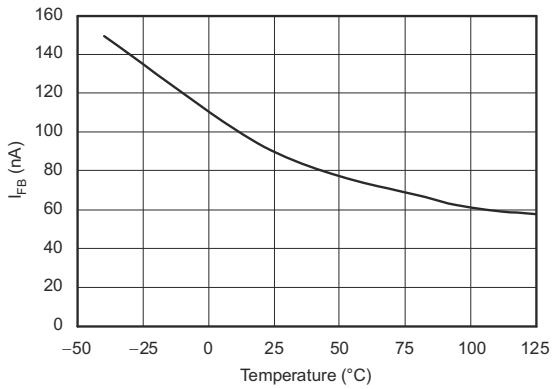



New silicon

**Figure 5-48. TPS73101 RMS Noise Voltage vs $C_{FB}$**

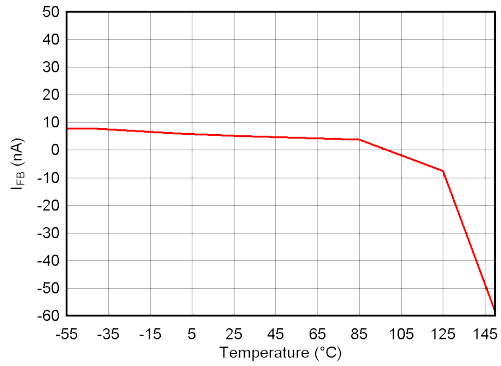
## 5.6 Typical Characteristics (continued)

For all voltage versions at $T_J$= 25°C, $V_{IN}$ = $V_{OUT(nom)}$ + 0.5V, $I_{OUT}$ = 10mA, $V_{EN}$ = 1.7V, and $C_{OUT}$ = 0.1µF (unless otherwise noted)



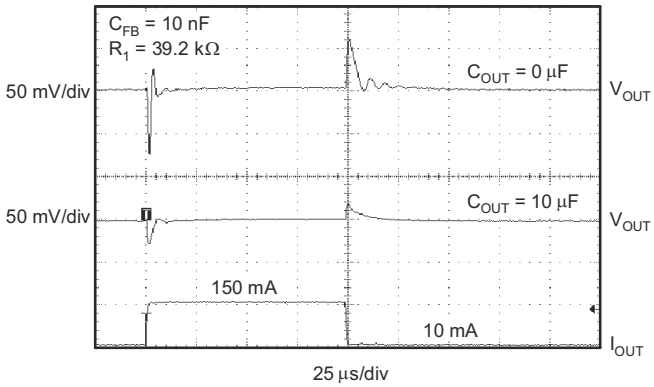

Legacy silicon

**Figure 5-49. TPS73101$I_{FB}$ vs Temperature**



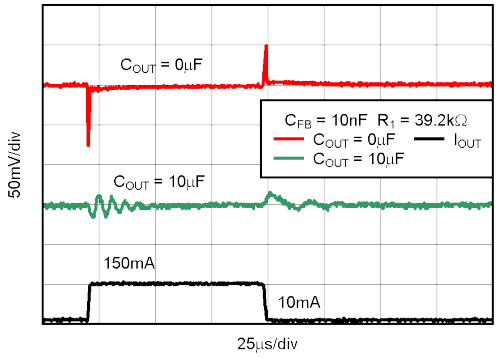

New silicon

**Figure 5-50. TPS73101$I_{FB}$ vs Temperature**



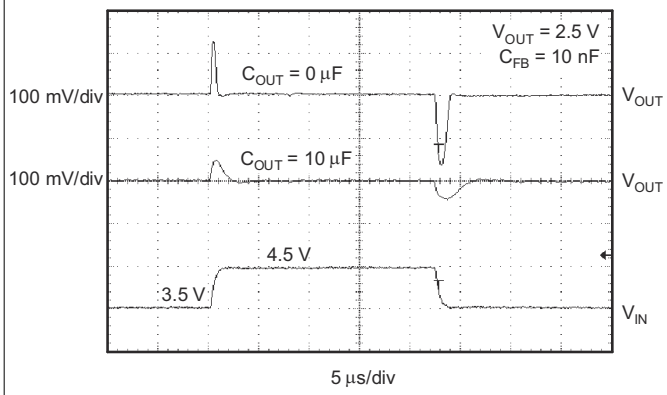

Legacy silicon

**Figure 5-51. TPS73101 Load Transient, Adjustable Version**



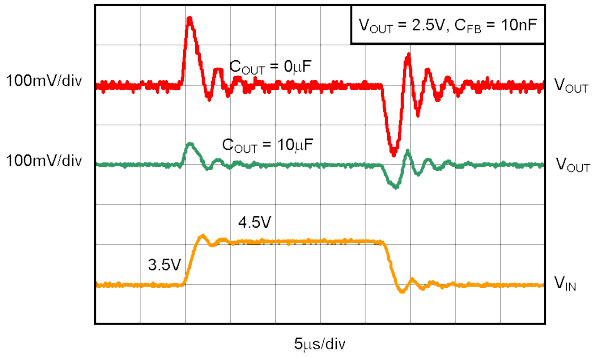

New silicon

**Figure 5-52. TPS73101 Load Transient, Adjustable Version**




Legacy silicon

**Figure 5-53. TPS73101 Line Transient, Adjustable Version**




New silicon

**Figure 5-54. TPS73101 Line Transient, Adjustable Version**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# 6 Detailed Description

## 6.1 Overview

The TPS731 low-dropout linear regulator operates down to an input voltage of 1.7V and supports output voltages down to 1.2V while sourcing up to 150mA of load current. This linear regulator uses an NMOS pass transistor with an integrated 4MHz charge pump to provide a dropout voltage of less than 100mV at full load current. This unique architecture also permits stable regulation over a wide range of output capacitors. In fact, the TPS731 does not require an output capacitor for stability. The increased insensitivity to the output capacitor value and type makes this linear regulator an excellent choice when powering a load where the effective capacitance is unknown.

The TPS731 also features a noise-reduction (NR) pin that allows for additional reduction of the output noise. With a noise-reduction capacitor of 0.01µF connected from the NR pin to GND, the TPS73115 output noise ranges as low as 12.75µ$V_{RMS}$. The low noise output featured by the TPS731 makes the device designed for powering VCOs or any other noise-sensitive load.

## 6.2 Functional Block Diagrams

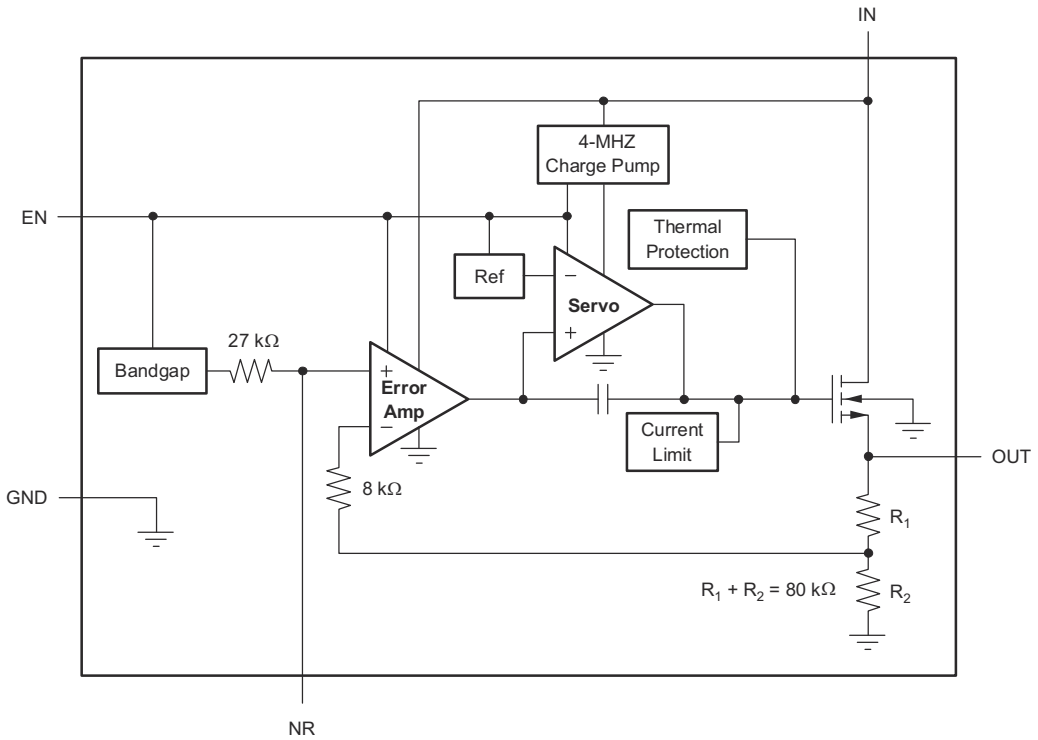
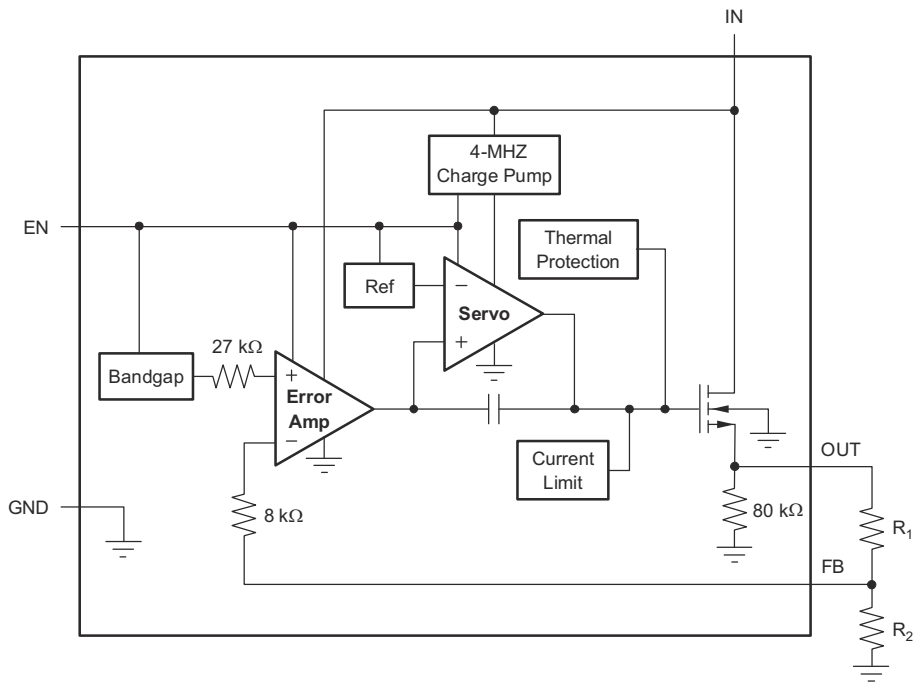



**Figure 6-1. Fixed-Voltage Version**




**Standard 1% Resistor Values for Common Output Voltages**

| $V_O$ | $R_1$ | $R_2$ |
|---|---|---|
| 1.2 V | Short | Open |
| 1.5 V | 23.2 kΩ | 95.3kΩ |
| 1.8 V | 28.0 kΩ | 56.2 kΩ |
| 2.5 V | 39.2kΩ | 36.5 kΩ |
| 2.8 V | 44.2 kΩ | 33.2 kΩ |
| 3.0 V | 46.4 kΩ | 30.9 kΩ |
| 3.3 V | 52.3 kΩ | 30.1 kΩ |

NOTE: $V_{OUT} = (R_1 + R_2)/R_2 \cdot 1.204$; $R_1 \| R_2 \cong 19\ k\Omega$ for best accuracy.

**Figure 6-2. Adjustable-Voltage Version**

## 6.3 Feature Description

### *6.3.1 Output Noise*

A precision band-gap reference is used to generate the internal reference voltage, $V_{REF}$. This reference is the dominant noise source within the TPS731xx and it generates approximately 32µ$V_{RMS}$ (10Hz to 100kHz) at the reference output (NR). The regulator control loop gains up the reference noise with the same gain as the reference voltage, so that the noise voltage of the regulator is approximately given by Equation 1:

$$V_{IN} = 32\mu V_{RMS} \times \frac{(R_1 + R_2)}{R_2} = 32\mu V_{RMS} \times \frac{V_{OUT}}{V_{REF}} \quad (1)$$

Because the value of $V_{REF}$ is 1.2V, this relationship reduces to Equation 2 for the case of no $C_{NR}$.

$$V_N(\mu V_{RMS}) = 27\left(\frac{\mu V_{RMS}}{V}\right) \times V_{OUT}(V) \quad (2)$$

An internal 27kΩ resistor in series with the noise reduction pin (NR) forms a low-pass filter for the voltage reference when an external noise reduction capacitor, $C_{NR}$, is connected from NR to ground. For $C_{NR}$ = 10nF, the total noise in the 10Hz to 100kHz bandwidth is reduced by a factor of approximately 3.2, giving the approximate relationship shown in Equation 3 for $C_{NR}$ = 10nF.

$$V_N(\mu V_{RMS}) = 8.5\left(\frac{\mu V_{RMS}}{V}\right) \times V_{OUT}(V) \quad (3)$$

This noise reduction effect is shown as *RMS Noise Voltage vs $C_{NR}$* in the Typical Characteristics section.

The TPS73101 adjustable version does not have the NR pin available. However, connecting a feedback capacitor, $C_{FB}$, from the output to the feedback pin (FB) reduces output noise and improves load transient performance.

The TPS731xx uses an internal charge pump to develop an internal supply voltage sufficient to drive the gate of the NMOS pass element above $V_{OUT}$. The charge pump generates approximately 250µV of switching noise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at approximately 4MHz; however, charge-pump noise contribution is negligible at the output of the regulator for most values of $I_{OUT}$ and $C_{OUT}$.

#### 6.3.2 Internal Current Limit

The TPS731xx internal current limit helps protect the regulator during fault conditions. Foldback current limit helps to protect the regulator from damage during output short-circuit conditions by reducing current limit when $V_{OUT}$ drops below 0.5V. See Figure 5-17.

Note from Figure 5-17 that approximately –0.2V of $V_{OUT}$ results in a current limit of 0mA. Therefore, if OUT is forced below –0.2V before EN goes high, the device may not start up. In applications that work with both a positive and negative voltage supply, the TPS731xx should be enabled first.

#### 6.3.3 Enable Pin and Shutdown

The enable pin (EN) is active high and is compatible with standard TTL-CMOS levels. A $V_{EN}$ below 0.5V (maximum) turns the regulator off and drops the GND pin current to approximately 10nA. When EN is used to shutdown the regulator, all charge is removed from the pass transistor gate. A $V_{EN}$ above 1.7V (minimum) turns the regulator on and the output ramps back up to a regulated $V_{OUT}$ (see Figure 5-39).

When shutdown capability is not required, connect EN to $V_{IN}$. However, the pass transistor potentially does not discharge using this configuration, thus leaving the pass transistor left on (enhanced) for a significant time after removing $V_{IN}$. This scenario results in reverse current flow (if the IN pin is low impedance) and faster ramp times upon power up. In addition, for $V_{IN}$ ramp times slower than a few milliseconds, the output potentially overshoots upon power up.

The current limit foldback prevents device start-up under some conditions. See the *Internal Current Limit* section.

#### 6.3.4 Reverse Current

The NMOS pass element of the TPS731xx provides inherent protection against current flow from the output of the regulator to the input when the gate of the pass device is pulled low. To ensure that all charge is removed from the gate of the pass element, the EN pin must be driven low before the input voltage is removed. If this is not done, the pass element may be left on due to stored charge on the gate.

After the EN pin is driven low, no bias voltage is needed on any pin for reverse current blocking. The reverse current is specified as the current flowing out of the IN pin due to voltage applied on the OUT pin. There will be additional current flowing into the OUT pin due to the 80kΩ internal resistor divider to ground (see Figure 6-1 and Figure 6-2).

For the TPS73101, reverse current may flow when $V_{FB}$ is more than 1.0V above $V_{IN}$.

### 6.4 Device Functional Modes

#### 6.4.1 Normal Operation With $1.7V \le V_{IN} \le 5.5V$ and $V_{EN} \ge 1.7V$

The TPS731xx family requires an input voltage of at least 1.7V to function properly and attempt to maintain regulation.

When operating the device near 5.5V, take care to suppress any transient spikes that may exceed the 6.0V absolute maximum voltage rating. The device should never operate at a DC voltage greater than 5.5V.

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# 7 Application and Implementation

**Note**

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 7.1 Application Information

The TPS731xx belongs to a family of new generation LDO regulators that use an NMOS pass transistor to achieve ultra-low-dropout performance, reverse current blockage, and freedom from output capacitor constraints. These features, combined with low noise and an enable input, make the TPS731xx ideal for portable applications. This regulator family offers a wide selection of fixed output voltage versions and an adjustable output version. All versions have thermal and over-current protection, including foldback current limit.

## 7.2 Typical Application

Figure 7-1 shows the basic circuit connections for the fixed-voltage models. Figure 7-2 gives the connections for the adjustable output version (TPS73101).

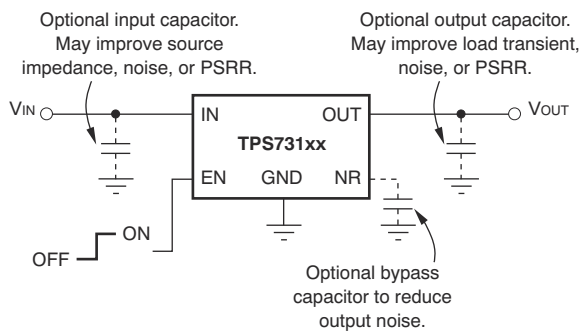


**Figure 7-1. Typical Application Circuit for Fixed-Voltage Versions**

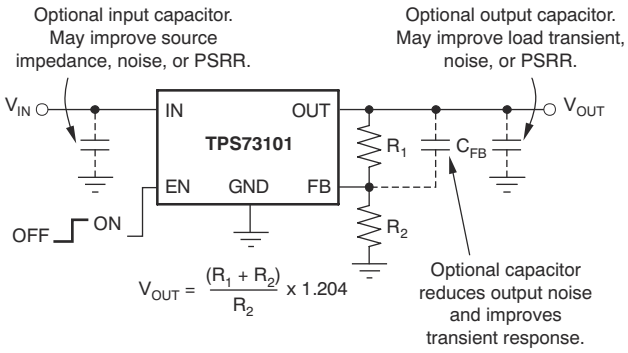


**Figure 7-2. Typical Application Circuit for Adjustable-Voltage Version**

### *7.2.1 Design Requirements*

$R_1$ and $R_2$ can be calculated for any output voltage using the formula shown in Figure 7-2. Sample resistor values for common output voltages are shown in Figure 6-2.

For best accuracy, make the parallel combination of $R_1$ and $R_2$ approximately equal to 19kΩ. This 19kΩ, in addition to the internal 8kΩ resistor, presents the same impedance to the error amp as the 27kΩ bandgap reference output. This impedance helps compensate for leakages into the error amp terminals.


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### 7.2.2 Detailed Design Procedure

#### 7.2.2.1 Input and Output Capacitor Requirements

Although an input capacitor is not required for stability, it is good analog design practice to connect a 0.1µF to 1µF, low ESR capacitor across the input supply near the regulator. This counteracts reactive input sources and improves transient response, noise rejection, and ripple rejection. A higher-value capacitor may be necessary if large, fast rise-time load transients are anticipated or the device is located several inches from the power source.

#### 7.2.2.2 Dropout Voltage

The TPS731xx uses an NMOS pass transistor to achieve extremely low dropout. When ($V_{IN}$ – $V_{OUT}$) is less than the dropout voltage ($V_{DO}$), the NMOS pass device is in its linear region of operation and the input-to-output resistance is the $R_{DS(on)}$ of the NMOS pass element.

For large step changes in load current, the TPS731xx requires a larger voltage drop from $V_{IN}$ to $V_{OUT}$ to avoid degraded transient response. The boundary of this transient dropout region is approximately twice the DC dropout. Values of $V_{IN}$ – $V_{OUT}$ above this line insure normal transient response.

Operating in the transient dropout region can cause an increase in recovery time. The time required to recover from a load transient is a function of the magnitude of the change in load current rate, the rate of change in load current, and the available headroom ($V_{IN}$ to $V_{OUT}$ voltage drop). Under worst-case conditions [full-scale instantaneous load change with ($V_{IN}$ – $V_{OUT}$) close to DC dropout levels], the TPS731xx can take a couple of hundred microseconds to return to the specified regulation accuracy.

#### 7.2.2.3 Transient Response

The low open-loop output impedance provided by the NMOS pass element in a voltage follower configuration allows operation without an output capacitor for many applications. As with any regulator, the addition of a capacitor (nominal value 1µF) from the output pin (OUT) to ground will reduce undershoot magnitude but increase its duration. In the adjustable version, the addition of a capacitor, $C_{FB}$, from the OUT pin to the FB pin will also improve the transient response.

The TPS731xx does not have active pulldown when the output is overvoltage. This allows applications that connect higher voltage sources, such as alternate power supplies, to the output. This also results in an output overshoot of several percent if the load current quickly drops to zero when a capacitor is connected to the output. The duration of overshoot can be reduced by adding a load resistor. The overshoot decays at a rate determined by output capacitor $C_{OUT}$ and the internal and external load resistance. The rate of decay is given by Equation 4 and Equation 5:

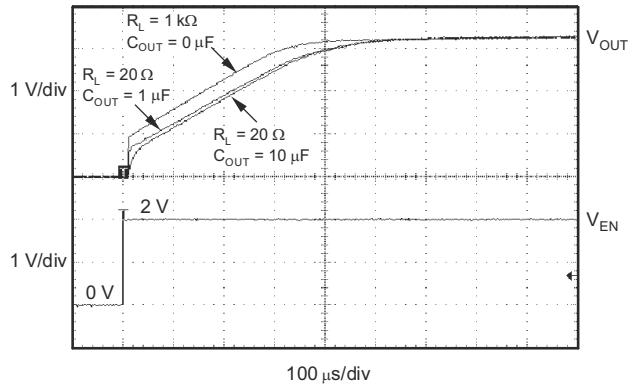
(Fixed-voltage version)

$$dV/dt = \frac{V_{OUT}}{C_{OUT} \times 80k\Omega \parallel R_{LOAD}} \tag{4}$$

(Adjustable-voltage version)

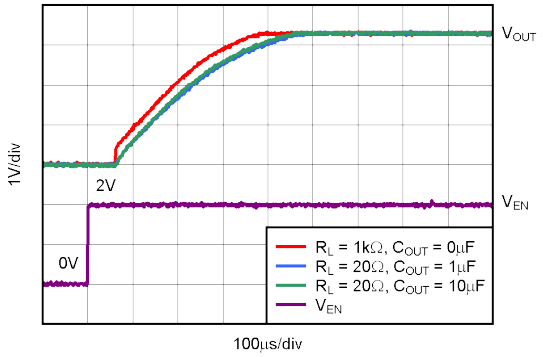
$$dV/dt = \frac{V_{OUT}}{C_{OUT} \times 80k\Omega \parallel (R_1 + R_2) \parallel R_{LOAD}} \tag{5}$$

### 7.2.3 Application Curves



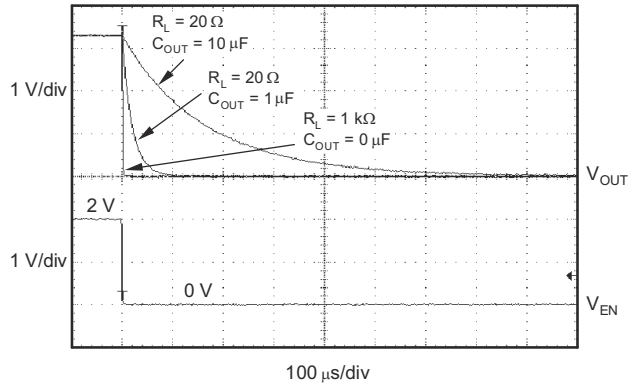

Legacy silicon

**Figure 7-3. TPS73133 Turn-On Response**



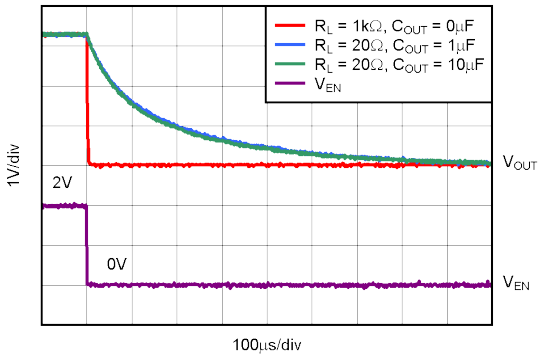

New silicon

**Figure 7-4. TPS73133 Turn-On Response**




Legacy silicon

**Figure 7-5. TPS73133 Turnoff Response**




New silicon

**Figure 7-6. TPS73133 Turn-Off Response**

## 7.3 Power Supply Recommendations

This device is designed to operate from an input voltage supply range between 1.7V and 5.5V. The input voltage range provides adequate headroom for the device to have a regulated output. Verify this input supply must is regulated. If the input supply is noisy, additional input capacitors with low ESR help improve output noise performance.

## 7.4 Layout

### 7.4.1 Layout Guidelines

To improve AC performance (such as PSRR, output noise, and transient response), design the PCB with ground plane connections for $V_{IN}$ and $V_{OUT}$ capacitors. Connect the ground plane at the ground pin (GND) of the device. In addition, verify the ground connection for the bypass capacitor connects directly to the GND pin of the device.

#### 7.4.1.1 Thermal Considerations

Thermal protection disables the output when the junction temperature rises to approximately 160°C, allowing the device to cool. When the junction temperature cools to approximately 140°C, the output circuitry is again enabled. Depending on power dissipation, thermal resistance, and ambient temperature, the thermal protection circuit may cycle on and off. This limits the dissipation of the regulator, protecting it from damage due to overheating.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Any tendency to activate the thermal protection circuit indicates excessive power dissipation or an inadequate heatsink. For reliable operation, junction temperature should be limited to 125°C maximum. To estimate the margin of safety in a complete design (including heatsink), increase the ambient temperature until the thermal protection is triggered; use worst-case loads and signal conditions. For good reliability, thermal protection should trigger at least 35°C above the maximum expected ambient condition of your application. This produces a worst-case junction temperature of 125°C at the highest expected ambient temperature and worst-case load.

The internal protection circuitry of the TPS731xx has been designed to protect against overload conditions. It was not intended to replace proper heatsinking. Continuously running the TPS731xx into thermal shutdown degrades device reliability.

#### 7.4.1.2 Power Dissipation

The ability to remove heat from the die is different for each package type, presenting different considerations in the PCB layout. The PCB area around the device that is free of other components moves the heat from the device to the ambient air. Performance data for JEDEC boards are shown in the *Thermal Information* table. Using heavier copper increases the effectiveness in removing heat from the device.

Power dissipation depends on input voltage and load conditions. Power dissipation ($P_D$) is equal to the product of the output current times the voltage drop across the output pass transistor ($V_{IN}$ to $V_{OUT}$):

$$P_D = (V_{IN} - V_{OUT}) \times I_{OUT} \tag{6}$$

Power dissipation is minimized by using the lowest possible input voltage necessary to provide the required output voltage.

### *7.4.2 Layout Examples*

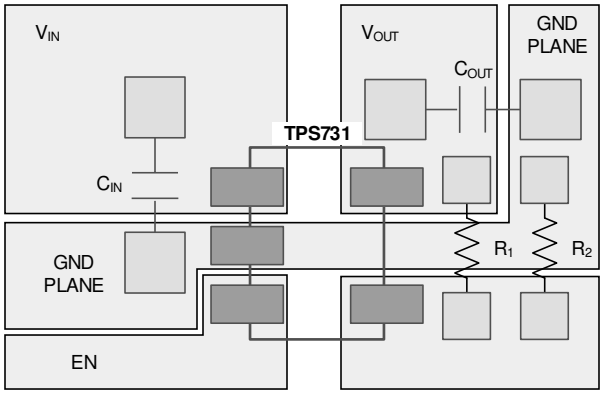


**Figure 7-7. Example Layout for the Adjustable-Output Version (DBV Package)**

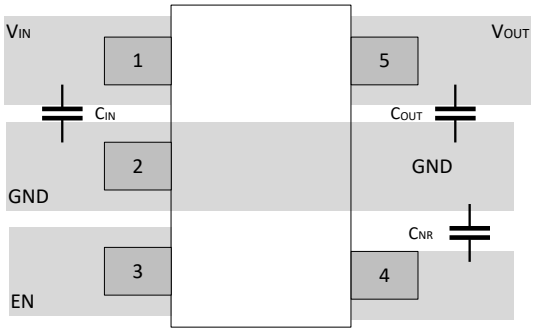


**Figure 7-8. Layout Example for the Fixed-Output Version (DBV Package)**

# 8 Device and Documentation Support

## 8.1 Device Support

### *8.1.1 Development Support*

#### 8.1.1.1 Spice Models

Computer simulation of circuit performance using SPICE is often useful when analyzing the performance of analog circuits and systems. A SPICE model for the TPS731 is available through the product folders under *Tools & Software*.

### *8.1.2 Device Nomenclature*

**Table 8-1. Available Options**

| PRODUCT[(1)] | DESCRIPTION |
|---|---|
| TPS731**xx yyy z (M3)** | **xx** is the nominal output voltage (for example, 25 = 2.5V; 01 = Adjustable).<br>**yyy** is the package designator.<br>**z** is the package quantity.<br>**M3** is a suffix designator for devices that only use the latest manufacturing flow (CSO: RFB). Devices without this suffix ship with the *legacy silicon* (CSO: DLN) or the *new silicon* (CSO: RFB). The reel packaging label provides CSO information to distinguish which silicon is used. Device performance for new and legacy silicon is denoted throughout the document. |

(1) For the most current package and ordering information see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

## 8.2 Documentation Support

### *8.2.1 Related Documentation*

For related documentation, see the following:

- Texas Instruments, *Solder Pad Recommendations for Surface-Mount Devices* application note.

## 8.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

## 8.4 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

## 8.5 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

## 8.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 8.7 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.


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## 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision O (August 2025) to Revision P (April 2026) | Page |
|---|---|
| • Added silicon 5V output ground current specification | 5 |
| • Added silicon 5V output ground pin current at maximum load specification | 5 |

| Changes from Revision N (December 2015) to Revision O (August 2025) | Page |
|---|---|
| • Updated the numbering format for tables, figures, and cross-references throughout the document | 1 |
| • Changed entire document to align with current family format | 1 |
| • Added new silicon (M3) devices to document | 1 |
| • Added nomenclature distinguishing between new silicon and legacy silicon information throughout document | 1 |
| • Changed *Applications* | 1 |
| • Added new silicon DBV thermals | 4 |
| • Changed VFB typical value | 5 |
| • Added new silicon ground pin current spec | 5 |
| • Added new silicon shutdown current spec | 5 |
| • Added new silicon curves to *Typical Characteristics* section | 6 |
| • Added $V_{EN}$ above 1.7V discussion to *Enable Pin and Shutdown* section | 17 |
| • Added new silicon curves to *Application Curves* section | 20 |
| • Changed *Layout Guidelines* section | 20 |
| • Changed *JEDEC low- and high-K boards* to *JEDEC boards* in *Power Dissipation* section | 21 |
| • Added *Layout Example for the Fixed-Output Version (DBV Package)* figure to *Layout Examples* | 21 |
| • Changed *Device Nomenclature* | 22 |

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package \| Pins | Package qty \| Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|---|---|---|---|---|---|---|---|---|---|
| TPS73101DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVRG4 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVRG4.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVTG4 | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS73101DBVTG4.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PWYQ |
| TPS731125DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | BYX |
| TPS731125DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | BYX |
| TPS731125DBVT | Obsolete | Production | SOT-23 (DBV) \| 5 | - | - | Call TI | Call TI | -40 to 125 | BYX |
| TPS73115DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T31 |
| TPS73115DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T31 |
| TPS73115DBVRG4 | NRND | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T31 |
| TPS73115DBVRG4.A | NRND | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T31 |
| TPS73115DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T31 |
| TPS73118DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVR1G4 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVR1G4.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVTG4 | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73118DBVTG4.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T32 |
| TPS73125DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73125DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73125DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | PHWI |

| Orderable part number | Status (1) | Material type (2) | Package \| Pins | Package qty \| Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|---|---|---|---|---|---|---|---|---|---|
| TPS73125DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73125DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73125DBVTG4 | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73125DBVTG4.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | PHWI |
| TPS73130DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T33 |
| TPS73130DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T33 |
| TPS73130DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T33 |
| TPS73130DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T33 |
| TPS73130DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T33 |
| TPS73131DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | BYS |
| TPS73131DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | BYS |
| TPS73131DBVT | Obsolete | Production | SOT-23 (DBV) \| 5 | - | - | Call TI | Call TI | -40 to 125 | BYS |
| TPS73132DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T52 |
| TPS73132DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T52 |
| TPS73132DBVT | Obsolete | Production | SOT-23 (DBV) \| 5 | - | - | Call TI | Call TI | -40 to 125 | T52 |
| TPS73133DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVRG4 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVRG4.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVTG4 | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73133DBVTG4.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T34 |
| TPS73150DBVR | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVR.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVRG4 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVRG4.A | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | NIPDAU | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVRM3 | Active | Production | SOT-23 (DBV) \| 5 | 3000 \| LARGE T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVT | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T35 |
| TPS73150DBVT.A | Active | Production | SOT-23 (DBV) \| 5 | 250 \| SMALL T&R | Yes | SN | Level-1-260C-UNLIM | -40 to 125 | T35 |

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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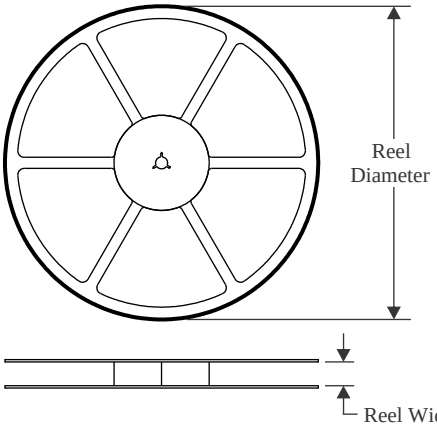
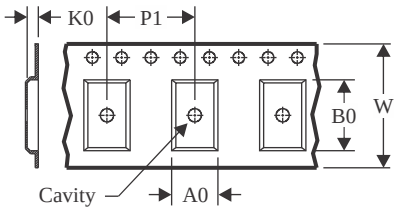
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION

**REEL DIMENSIONS**

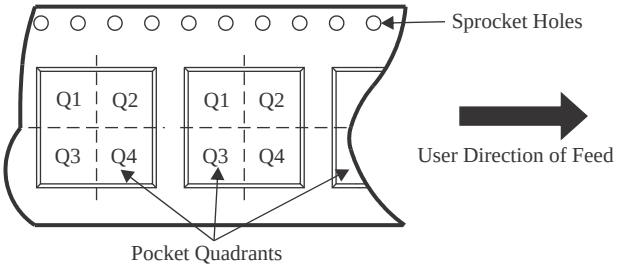



**TAPE DIMENSIONS**




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**

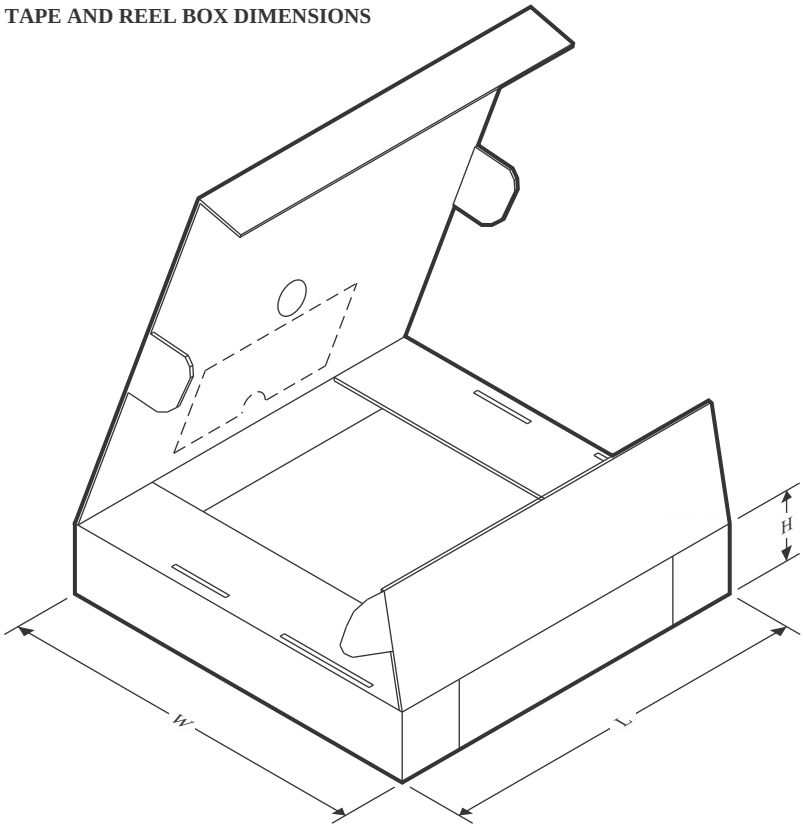



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| TPS73101DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73101DBVRG4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73101DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73101DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73101DBVTG4 | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS731125DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73115DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73115DBVRG4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.3 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73115DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73118DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73118DBVR1G4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73118DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73118DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73118DBVTG4 | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73125DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73125DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| TPS73125DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73125DBVTG4 | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73130DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73130DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73130DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73131DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73132DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73133DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73133DBVRG4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73133DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73133DBVT | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73133DBVTG4 | SOT-23 | DBV | 5 | 250 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73150DBVR | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73150DBVRG4 | SOT-23 | DBV | 5 | 3000 | 178.0 | 9.0 | 3.23 | 3.17 | 1.37 | 4.0 | 8.0 | Q3 |
| TPS73150DBVRM3 | SOT-23 | DBV | 5 | 3000 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| TPS73150DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |

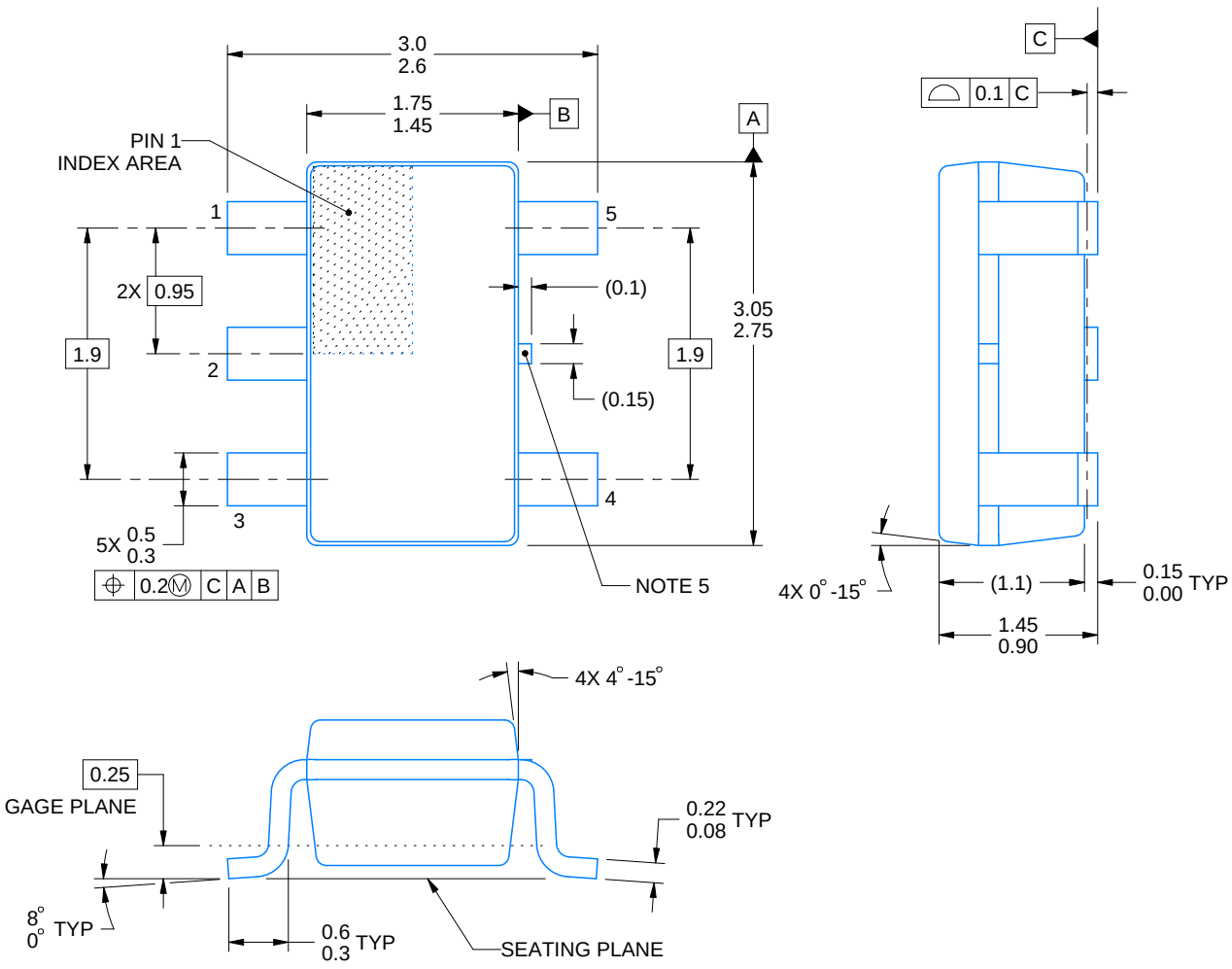
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| TPS73101DBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73101DBVRG4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73101DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73101DBVT | SOT-23 | DBV | 5 | 250 | 210.0 | 185.0 | 35.0 |
| TPS73101DBVTG4 | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS731125DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73115DBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73115DBVRG4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73115DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73118DBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73118DBVR1G4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73118DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73118DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS73118DBVTG4 | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS73125DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73125DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73125DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS73125DBVTG4 | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| TPS73130DBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73130DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73130DBVT | SOT-23 | DBV | 5 | 250 | 210.0 | 185.0 | 35.0 |
| TPS73131DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73132DBVR | SOT-23 | DBV | 5 | 3000 | 200.0 | 183.0 | 25.0 |
| TPS73133DBVR | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73133DBVRG4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73133DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73133DBVT | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS73133DBVTG4 | SOT-23 | DBV | 5 | 250 | 180.0 | 180.0 | 18.0 |
| TPS73150DBVR | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73150DBVRG4 | SOT-23 | DBV | 5 | 3000 | 180.0 | 180.0 | 18.0 |
| TPS73150DBVRM3 | SOT-23 | DBV | 5 | 3000 | 210.0 | 185.0 | 35.0 |
| TPS73150DBVT | SOT-23 | DBV | 5 | 250 | 210.0 | 185.0 | 35.0 |

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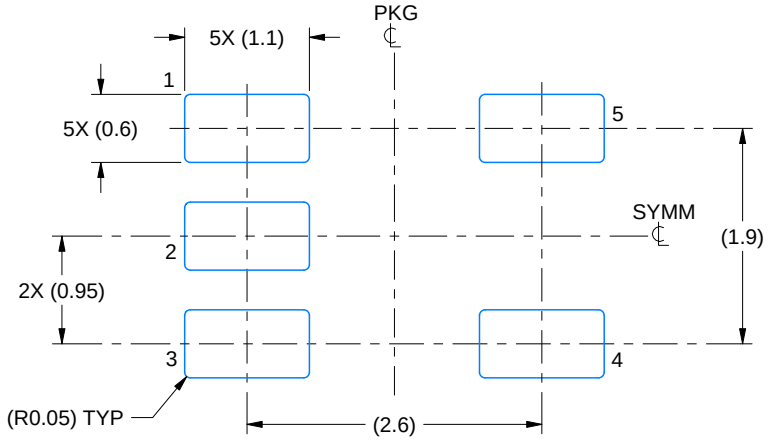
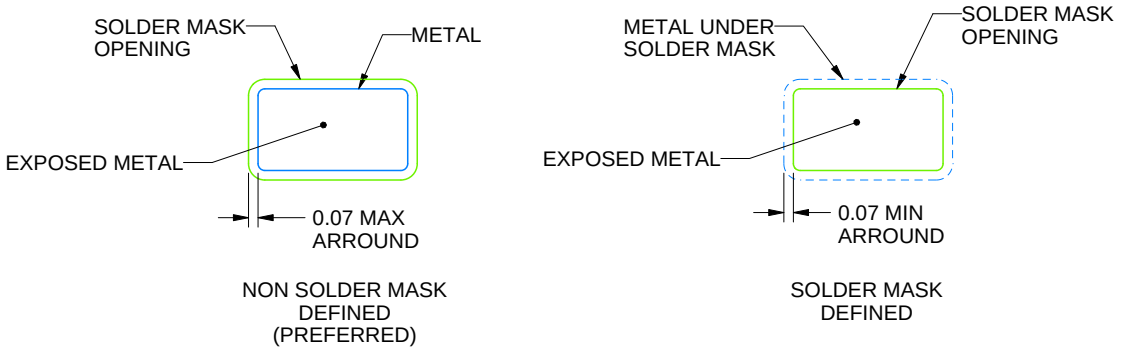
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Refernce JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X




SOLDER MASK DETAILS

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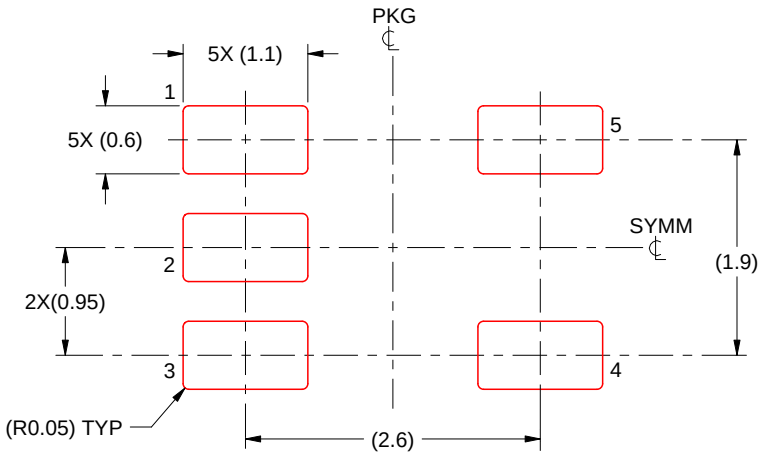
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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Last updated 10/2025